
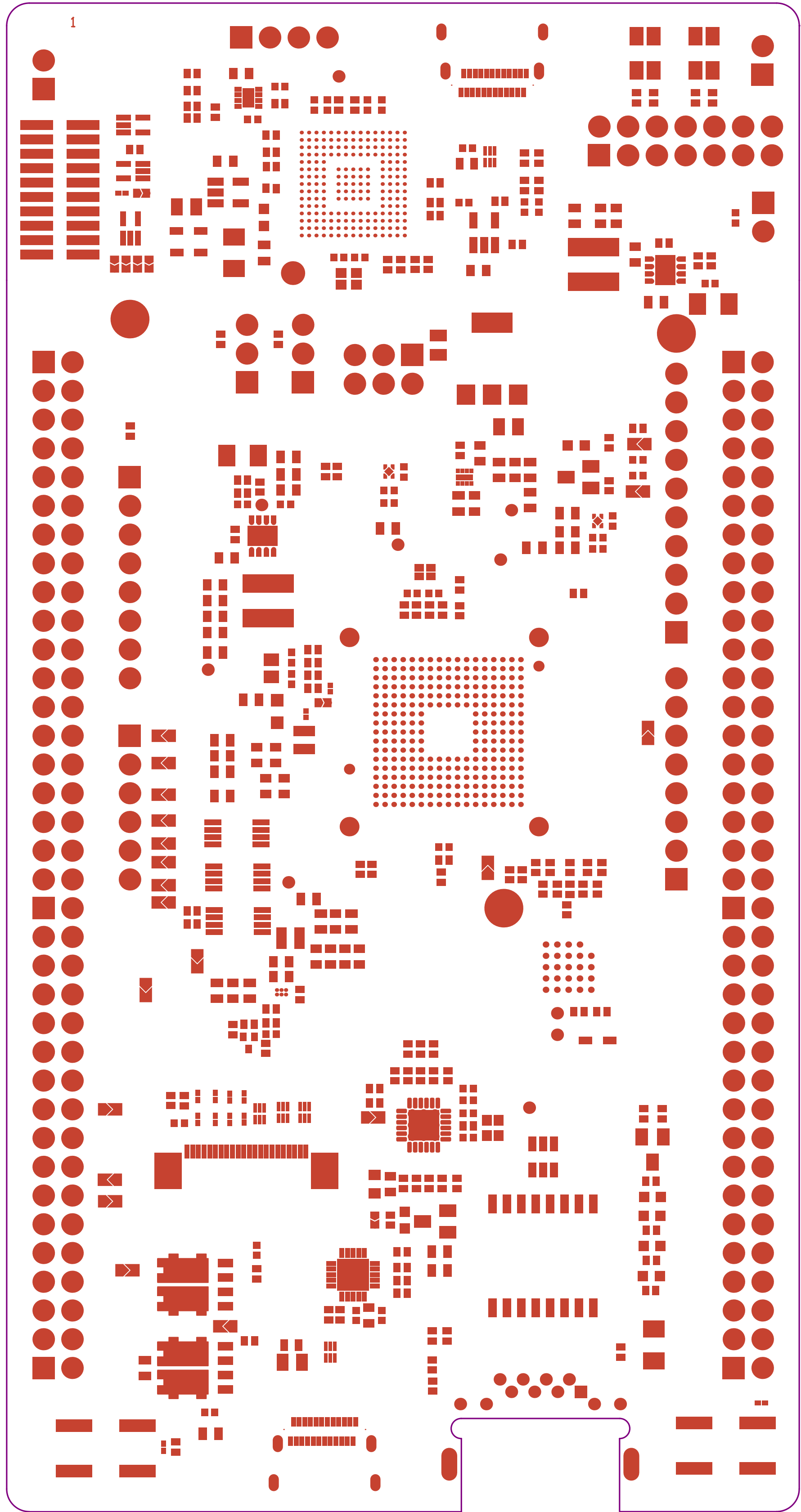

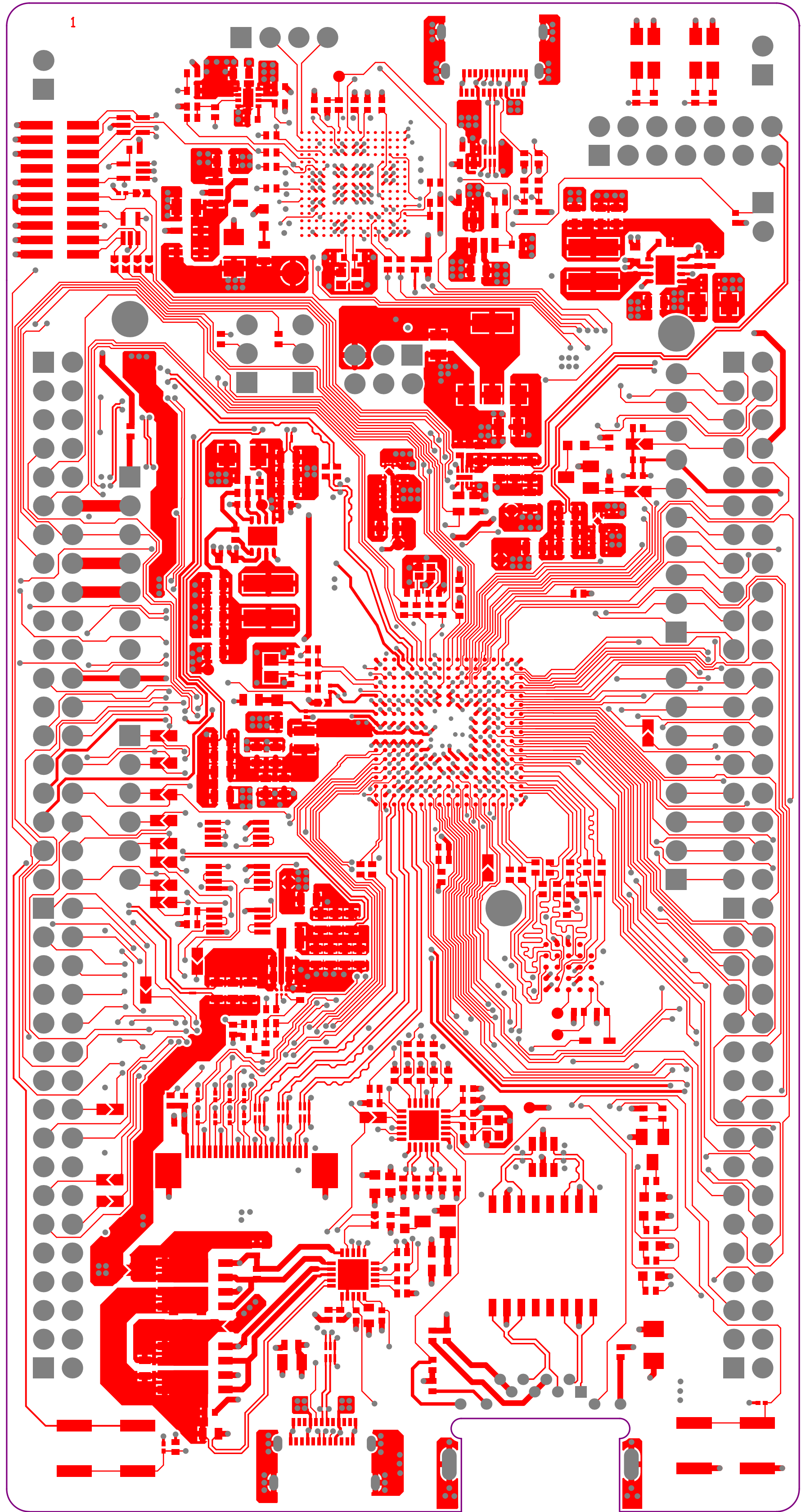



Project: STM32N6570-Nucleo		
Layer: Top Overlay	Gerber: .GTO	
Variant: N657X0Q	Ref: MB1940	
Date: 16-May-24	Rev: C	

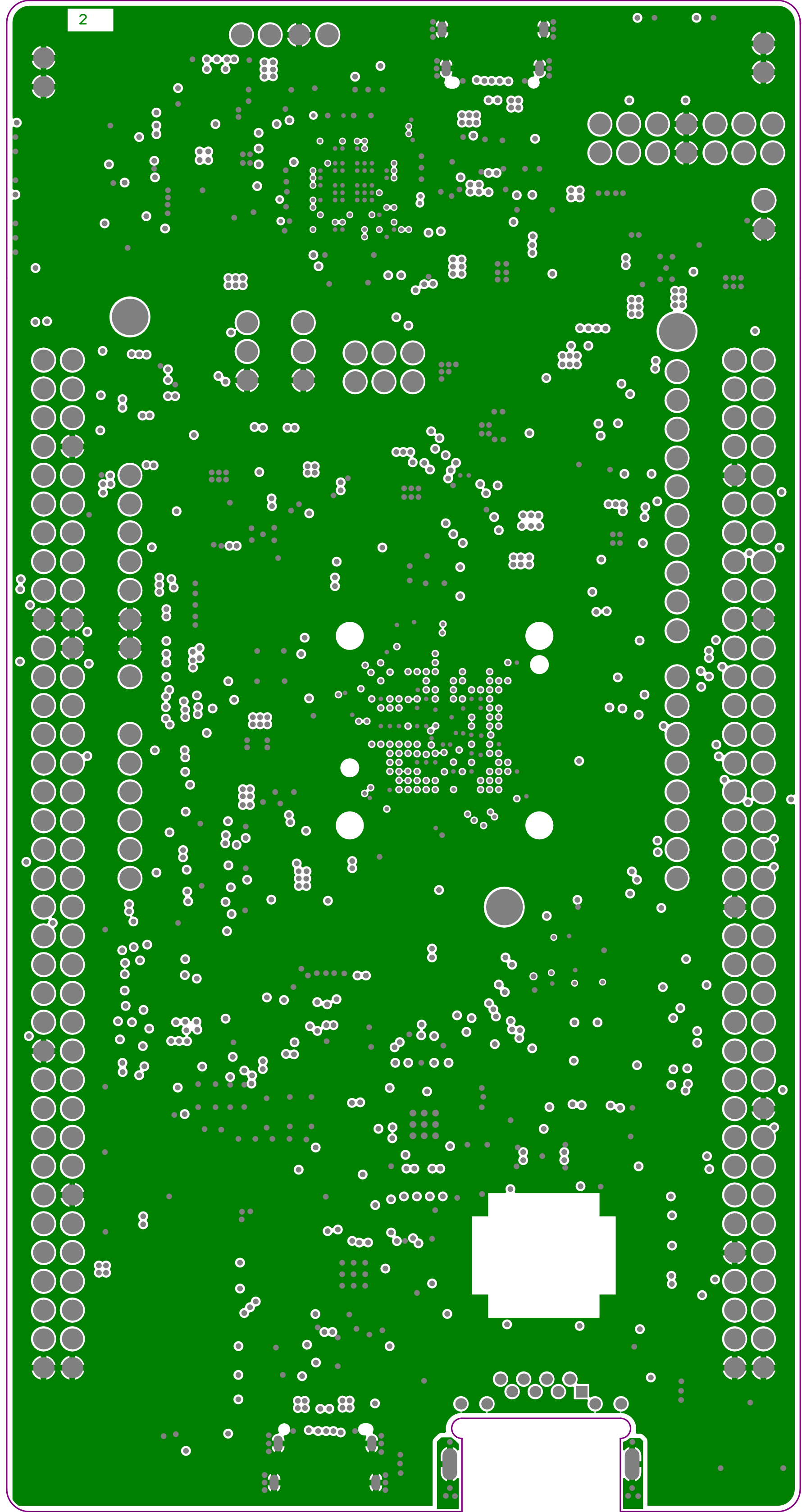



Project: STM32N6570-Nucleo		
Layer: <b>Top Solder</b>	Gerber: <b>.GTS</b>	
Variant: N657X0Q	Ref: MB1940	
Date: 16-May-24	Rev: C	



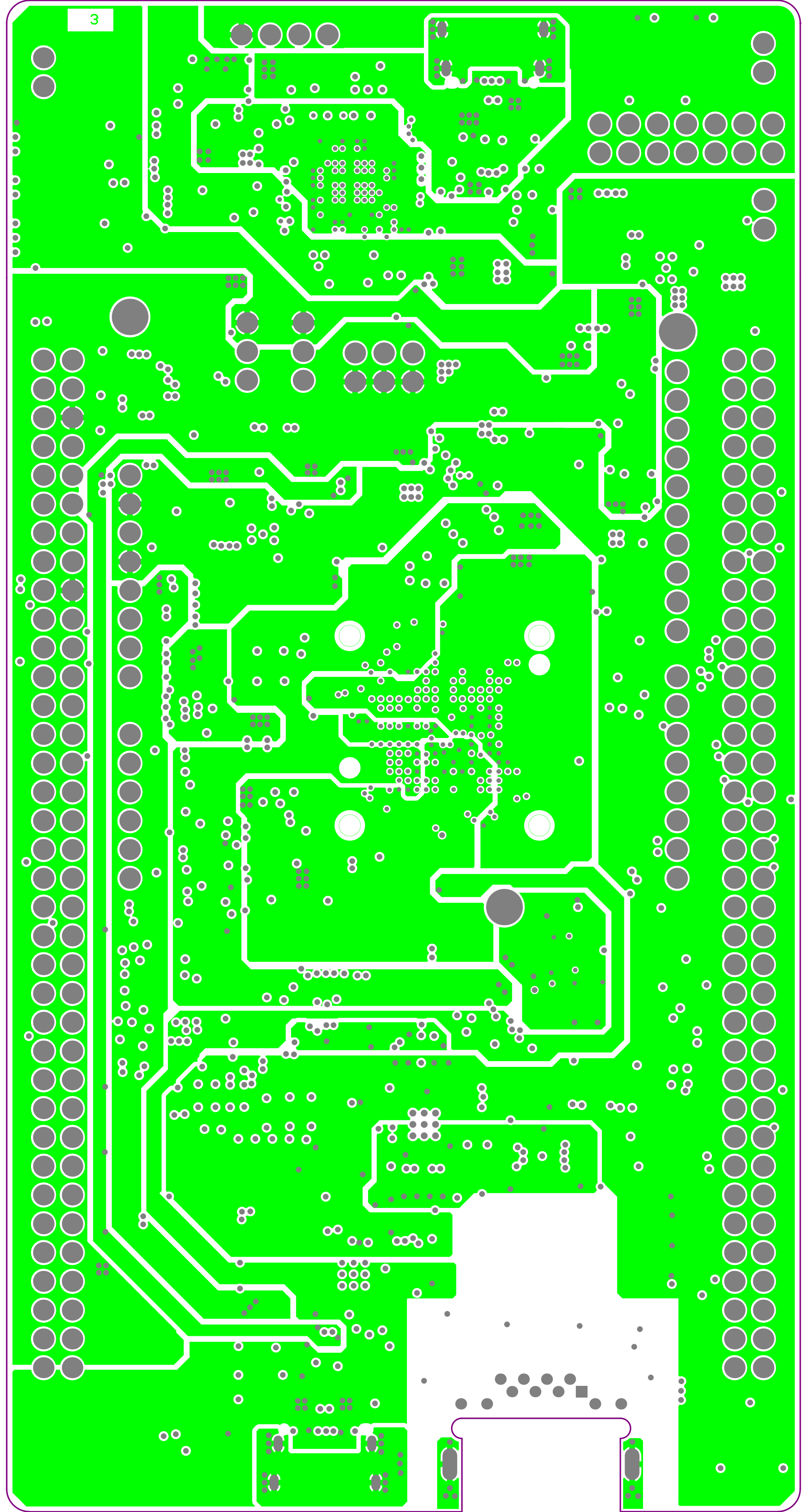
Project: STM32N6570-Nucleo		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: N657X0Q	Ref: MB1940	
Date: 16-May-24	Rev: C	




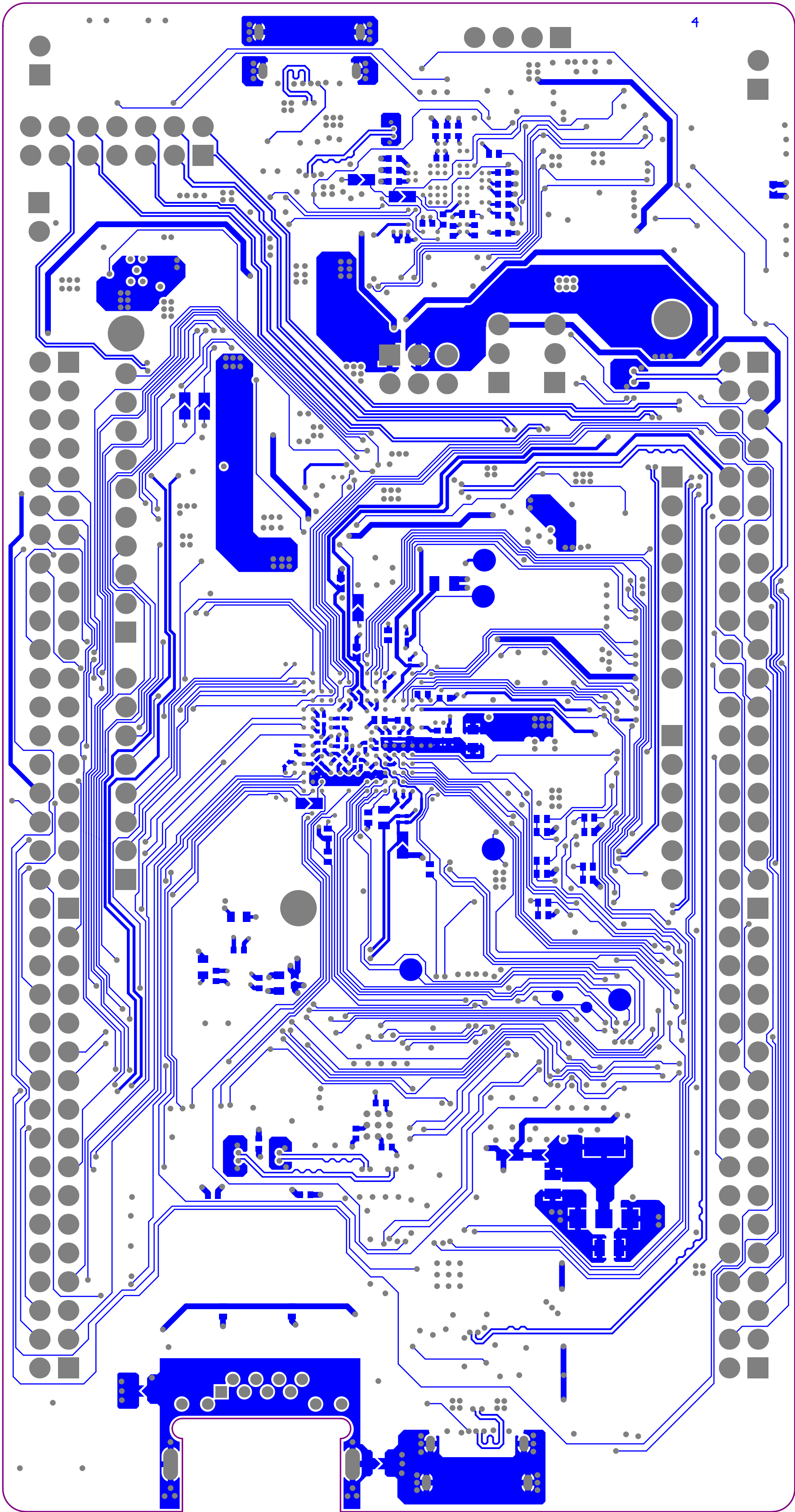


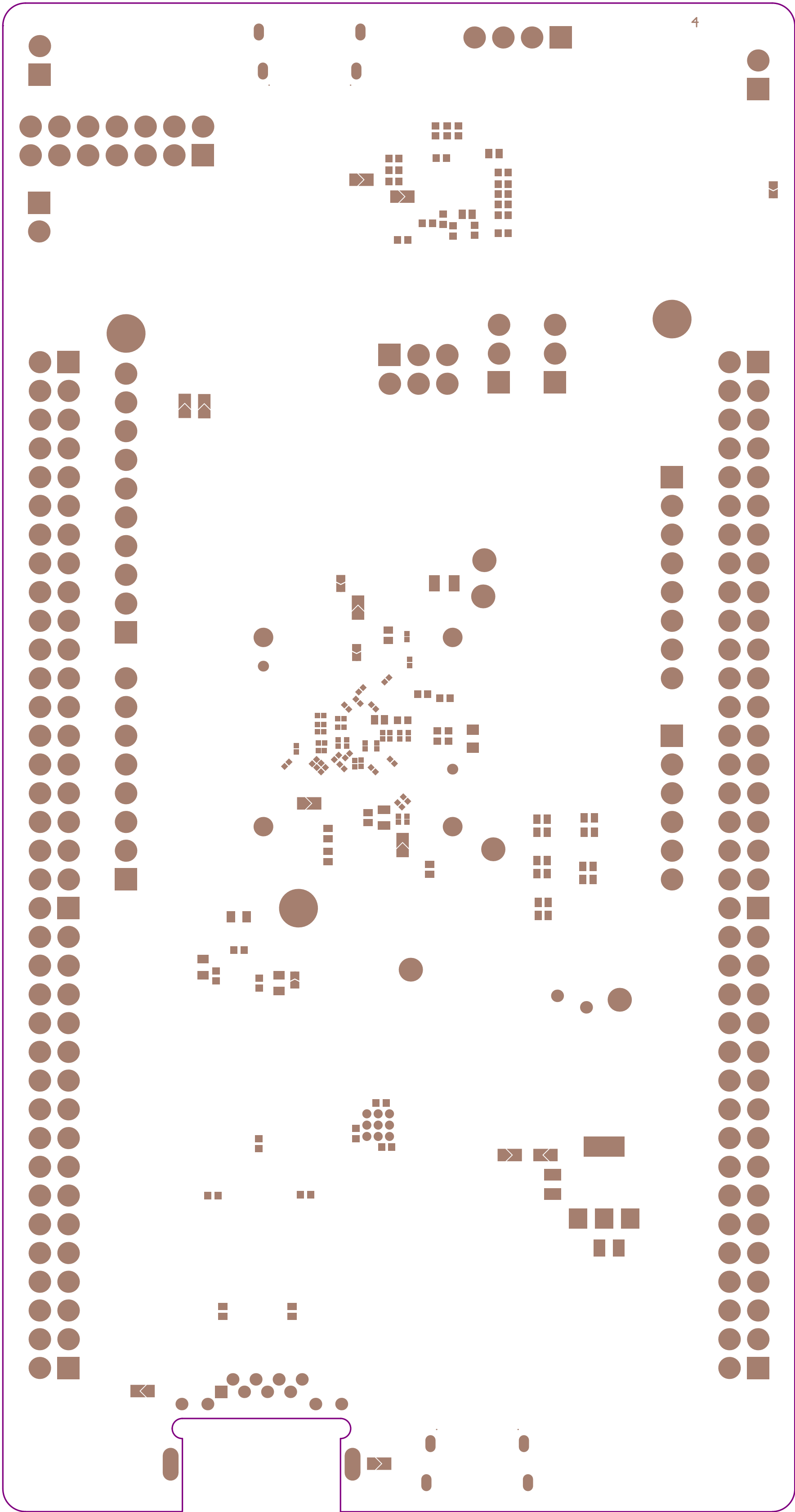
Project: STM32N6570-Nucleo		
Layer: L2_GND	Gerber: .G1	
Variant: N657X0Q	Ref: MB1940	
Date: 16-May-24	Rev: C	





Project: STM32N6570-Nucleo		
Layer: L3_VCC	Gerber: .G2	
Variant: N657X0Q	Ref: MB1940	
Date: 16-May-24	Rev: C	





Project: STM32N6570-Nucleo	
Layer: Bottom Solder	Gerber: .GBS
Variant: N657X0Q	Ref: MB1940
Date: 16-May-24	Rev: C

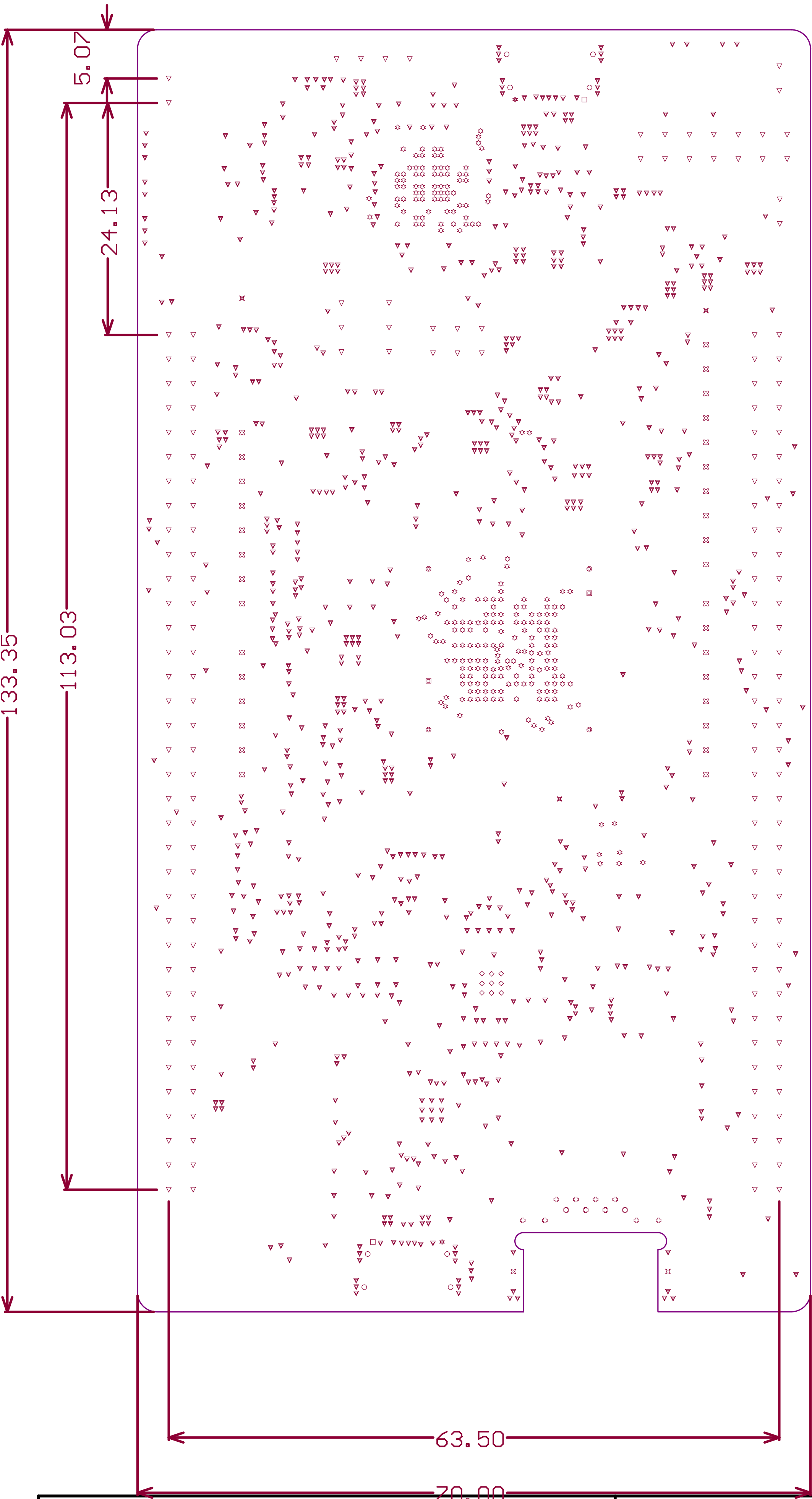
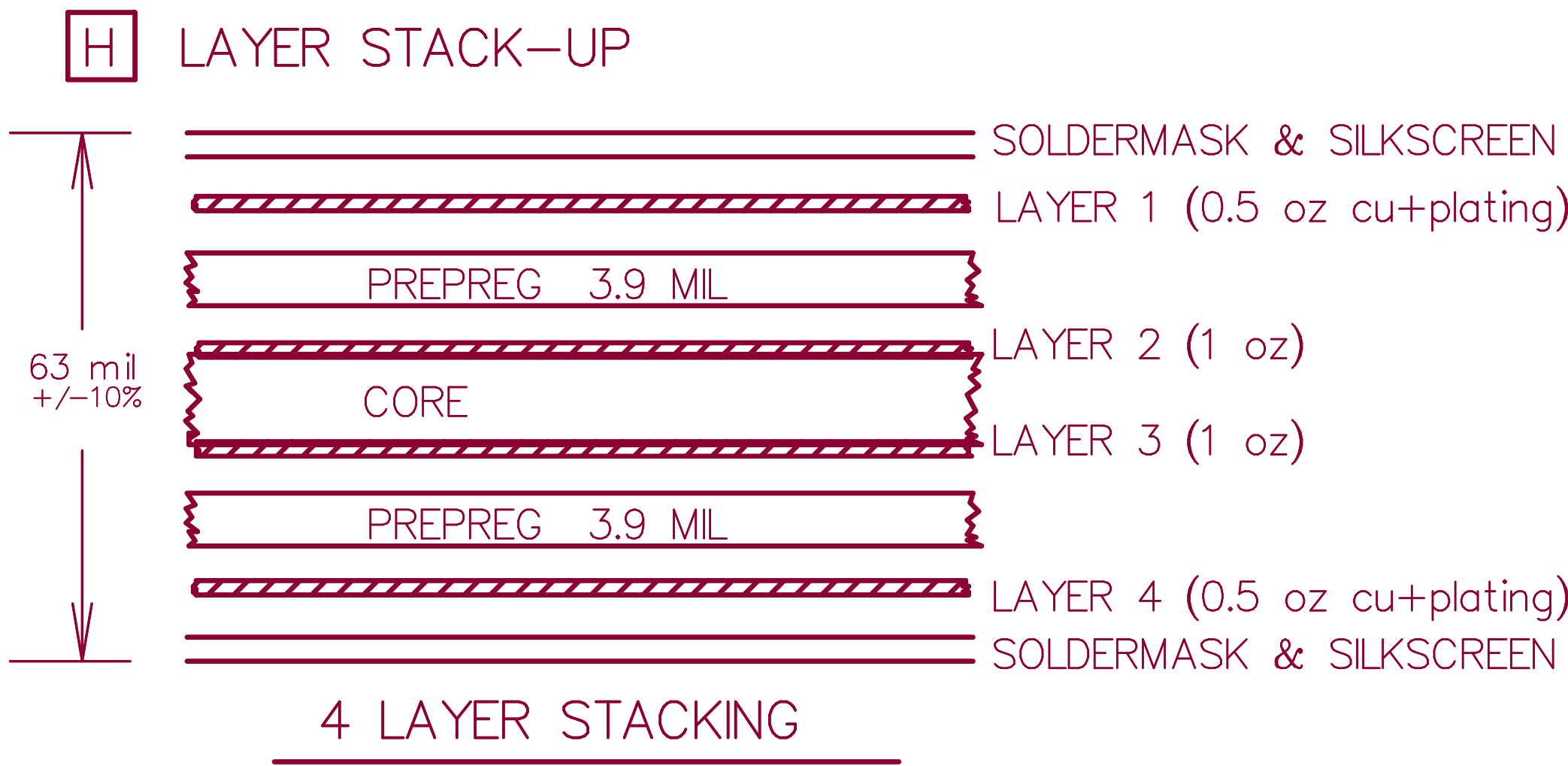






5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,4	4.0	N/A	55 OHM	N/A	+/-10%
1,4	6.1	8.9	N/A	90 OHM	+/-10%
1,4	5.1	9.9	N/A	100 OHM	+/-10%



PCB SPECIFICATIONS :			
A. MATERIAL :	FR-4	<input type="checkbox"/> TG-170	<input checked="" type="checkbox"/> TG-150
B. MATERIAL FAMILY :	N/A		<input type="checkbox"/> TG-140
C. SOLDERMASK COLOR :	<input type="checkbox"/> GREEN	<input checked="" type="checkbox"/> WHITE	<input type="checkbox"/> RED
D. SILKSCREEN COLOR :	<input type="checkbox"/> WHITE	<input type="checkbox"/> YELLOW	<input type="checkbox"/> BLACK
E. SURFACE FINISH :	<input checked="" type="checkbox"/> ENIG	<input type="checkbox"/> IMMERSION SILVER	<input type="checkbox"/> IMMERSION TIN
	<input type="checkbox"/> HASL	<input type="checkbox"/> HASL (PB-FREE)	<input type="checkbox"/> GOLDEN FINGER
F. IMPEDANCE CONTROL :	<input type="checkbox"/> NO	<input checked="" type="checkbox"/> YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)	
G. THROUGH VIA :	PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.		
	PLUG MATERIAL : <input checked="" type="checkbox"/> SOLDERMASK <input type="checkbox"/> NON-CONDUCTIVE EPOXY.		
H. STACK-UP :	SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.		

PCB : TYPE 3
ASPECT-RATIO, AXE Z :
6:1 to 8:1
MINIMUM PARAMETERS
DEFAULT
TRACKS : 0.0889mm
GAPS : 0.0838mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
	2	25.59mil (0.650mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn65m5			
	2	25.59mil (0.650mm)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn65_95m5			
	2	27.56mil (0.700mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r280_130h70_220r100m285_135			
	2	33.47mil (0.850mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn85m90(To12-2)		0.98mil (0.025mm)	0.98mil (0.025mm)
	3	125.98mil (3.200mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c320hn320			
	4	63.39mil (1.610mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn161m166(To15-5)		1.97mil (0.050mm)	1.97mil (0.050mm)
	8	19.69mil (0.500mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
	9	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30			
	12	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
	32	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
	180	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
	246	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v41h20m0mx0			
	881	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v51h25m0mx0			
	1383 Total										

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout